

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5669197	die dice chip ic integrated adj circuit package semiconductor silicon si substrate wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:35
L2	99807	inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:35
L3	69	inducting adj coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:36
L4	33625	heating adj coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:36
L5	18	(2 or 3) near2 pancake	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:40
L6	221611	megahertz mhz	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:40
L7	53	(2 or 3) with pancake	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:41
L8	12	6 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:41
L9	50411	induct\$4 near heat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:44
L10	37	4 same 9 same 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:44

L11	2888326	solder adj ball bga ball adj grid interconnect connection wire adj bond\$4 solder adj bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:44
L12	14	10 and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:47
L13	23	10 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:47
L14	15	13 not 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:47
L15	1392	((438/107) or (438/107) or (438/456)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/04 18:59
S11 8	99699	inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:05
S11 9	97	inducting near (element device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:39
S12 0	45369	eddy adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:05
S12 1	2150587	die dice chip ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:40
S12 2	2856201	solder adj ball bga ball adj grid interconnect connection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:41

S12 3	2881323	solder adj ball bga ball adj grid interconnect connection wire adj bond\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:05
S12 4	87211	solder adj ball bga ball adj grid wire adj bond\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:42
S12 5	0	S118 with S120 near2 S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:42
S12 6	0	S118 with S120 with S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:42
S12 7	1	S118 with S120 same S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:43
S12 8	1	S118 same S120 same S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:43
S12 9	118	S118 and S120 and S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:43
S13 0	101	S129 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 15:05
S13 1	322025	flux	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:50
S13 2	49564	(S120 or S121) with S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:48

S13 3	4645588	heat\$4 thermal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:48
S13 4	1933	(S120 or S131) with S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:48
S13 5	371	(S120 or S131) with S124 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:52
S13 6	353	S135 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:50
S13 7	116567	(em e-m electromagnet\$6 magnet\$6 electric\$6) adj flux	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 19:51
S13 8	3	(S120 or S137) with S124 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 20:15
S13 9	8	(S120 or S137) same S124 same S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:57
S14 0	940	(S120 or S137) with (interconnect\$4 bond\$4 lead wire wiring) with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/03 20:16
S14 1	13	(S120 or S137) with (interconnect\$4 bond\$4 lead wire wiring) with S121 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:53
S14 2	45393	eddy adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:16

S14 3	2152570	die dice chip ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:45
S14 4	4648077	heat\$4 thermal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:16
S14 5	116652	(em e-m electromagnet\$6 magnet\$6 electric\$6) adj flux	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:51
S14 6	2	(S142 or S145) with (interconnect\$4 bond\$4 lead wire wiring) near2 S143 with S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:16
S14 7	1	"20050142695".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:58
S14 8	885069	scan\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:58
S14 9	887346	scan\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 13:58
S15 0	1	S147 and S149	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:04
S15 1	99807	inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:05
S15 2	70318	heat\$4 near2 coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:05

S15 3	45393	eddy adj current	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:05
S15 4	2152570	die dice chip ic integrated adj circuit package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:44
S15 5	2816055	inductor heater heating coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:44
S15 6	5669197	die dice chip ic integrated adj circuit package semiconductor silicon si substrate wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:12
S15 7	1449	S155 with S156 near4 (S153 flux)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:49
S15 8	7032	S156 near2 (S153 flux)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:52
S15 9	116652	(em e-m electromagnet\$6 magnet\$6 electric\$6) adj flux	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:51
S16 0	1418	S156 near2 (S153 S145)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:55
S16 1	4806003	bond\$4 melt\$4 attach\$\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:54
S16 2	4794230	bond\$4 melt\$4 attach\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:54

S16 3	2362177	bond\$4 melt\$4 solder\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 15:02
S16 4	18	S156 near2 (S153 S145) with S163	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 15:01
S16 5	435	S156 with (S153 S145) same S163	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 14:57
S16 6	50411	induct\$4 near heat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:43
S16 7	4946025	bond\$4 melt\$4 solder\$4 attach\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 15:03
S16 8	104	S166 near2 S156 with S167	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:05
S16 9	90	S168 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:06
S17 0	2888326	solder adj ball bga ball adj grid interconnect connection wire adj bond\$4 solder adj bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:44
S17 1	149	S166 near2 S170	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:07
S17 2	139	S171 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:08

S17 3	0	S166 near2 S170 same S154	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:08
S17 4	15	S166 near2 S170 and S154	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:12
S17 5	14	S174 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:16
S17 6	336	S166 same S170 and S154	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:13
S17 7	5849863	die dice chip ic integrated adj circuit package semiconductor silicon si substrate wafer workpiece work adj piece	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:56
S17 8	340	S166 with S170 and S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:13
S17 9	99	S166 with S170 same S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:15
S18 0	66	S166 with S170 with S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:39
S18 1	95	S179 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:52
S18 2	0	attarwala-abbas.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:40

S18 3	79	attarwala.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:40
S18 4	9	attarwala-a\$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:44
S18 5	2	"20040195701".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:44
S18 6	0	(inductor coil) and S185	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:35
S18 7	2	(inductor coil heat\$4) and S185	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:45
S18 8	2	(inductor coil heat\$4 flux eddy) and S185	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:46
S18 9	1058	S166 near4 (mov\$4 scan\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:50
S19 0	208	S166 near (mov\$4 scan\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:50
S19 1	381	S166 with (mov\$4 scan\$4) with S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:56
S19 2	336	S191 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:53

S19 3	45	S166 with (scan\$4) with S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:53
S19 4	42	S193 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:58
S19 5	352	S166 with (mov\$4) with S177	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:57
S19 6	5669197	die dice chip ic integrated adj circuit package semiconductor silicon si substrate wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:35
S19 7	165	S166 with (mov\$4) with S196	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 16:57
S19 8	146	S197 and (@ad < "20031229")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 18:33